

*The first*

INTERNATIONAL  
CONFERENCE *on*

**MECHANICS, MATERIALS  
AND MECHATRONICS**

**ICM<sup>3</sup> - 2026** 23<sup>rd</sup> – 25<sup>th</sup> March, 2026

**Theme** : Mechanics, Materials and Mechatronics : Engineering the Future



## Certificate of Achievement

This is to certify that **Santosh Prasad** has been awarded the **Best Paper Presentation** for the paper titled *“Finite Element analysis of lumber spine (L3-L5) Loading under Pothole induced vibration in Powered Two wheelers”* (Paper ID: 73) at the **1<sup>st</sup> International Conference on Mechanics, Materials and Mechatronics**, held at Mahindra University, Hyderabad, from 23<sup>rd</sup> to 25<sup>th</sup> March 2026.

A handwritten signature in black ink, appearing to read 'Sebastian Uppapalli', is written over a light blue circular stamp.

(Dr. Sebastian Uppapalli)  
Conference Convener

A handwritten signature in black ink, appearing to read 'Debasis Chakraborty', is written over a light blue circular stamp.

(Prof. Debasis Chakraborty)  
Conference Chair